



ASMNUT.124C1

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Basol et al.  
Appl. No. : 10/663,318  
Filed : September 16, 2003  
For : CONDUCTIVE STRUCTURE  
FABRICATION PROCESS USING  
NOVEL LAYERED STRUCTURE  
AND CONDUCTIVE  
STRUCTURE FABRICATED  
THEREBY FOR USE IN MULTI-  
LEVEL METALLIZATION  
  
Examiner : Thao X. Le  
Group Art Unit : 2814

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

February 24, 2005

(Date)

Adeel S. Akhtar, Reg. No. 41,394

**RESPONSE TO OFFICE ACTION**

**Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on November 29, 2004, please amend the above-captioned application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.